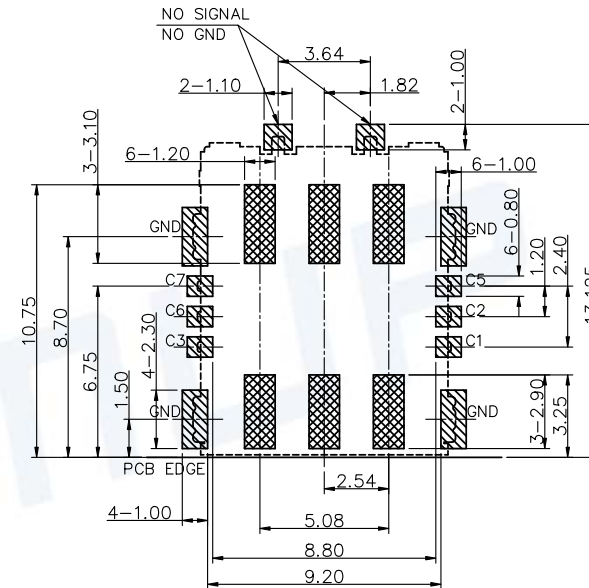
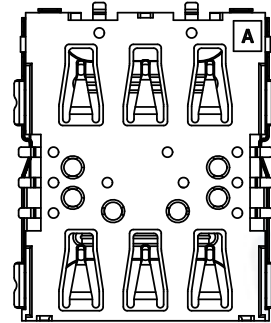
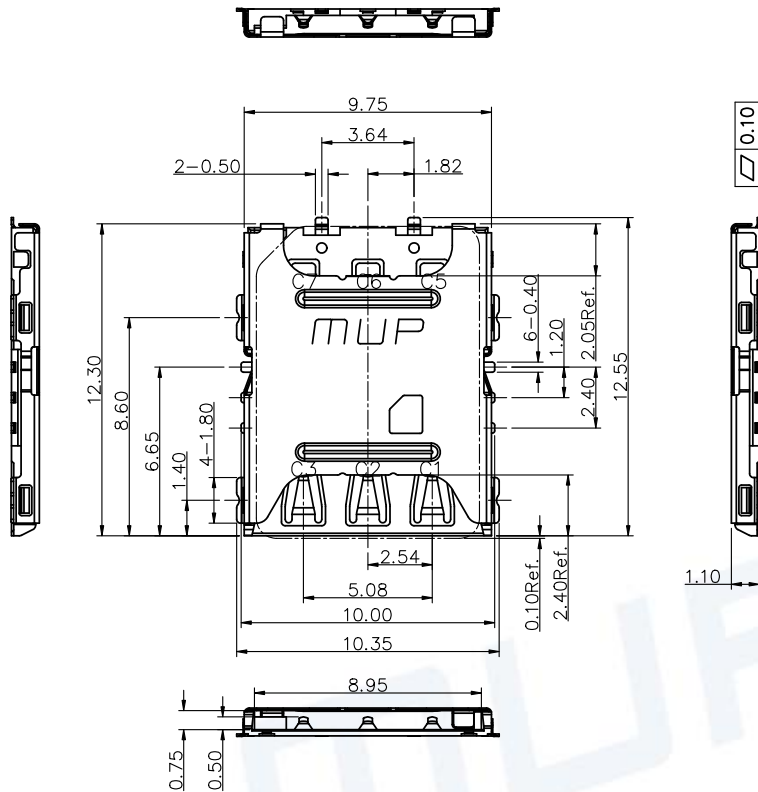


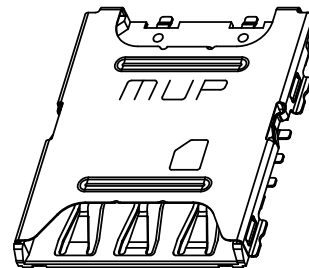
REV.	DESCRIPTION OF REVISIONS	APPR.	CHKD.	DRAW.	DATE
1	NEW			HXR	2024/11/20
2					



PIN NO.	FUNCTION
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ± 0.05)
Recommending of solder paste thickness 0.12mm

▨ PAD AREA ▩ KEEP OUT AREA
- - - CONNECTOR OUTLINE



TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: L9.75*W12.3*H1.1mm

Weight: Approx 0.15 g

Durability: 5000 cycles min.

2.Electrical Characteristics

Contact resistance: 100 m Ω Max

Insulation resistance: >1000 M Ω / 500V DC

3.Solderability

IR reflow: 250°C.5sec.Max

Manual soldering: 350°C, 3sec.Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity: 10%~+95%RH



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	High temperature UL94V-0	Black
2	CONTACT	6	Copper alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	Solder area:Gold plated

Unless otherwise specified, other tolerance are:

X	± 0.35	X*	$\pm 5^{\circ}$
X.X	± 0.25	X.X*	$\pm 4^{\circ}$
X.XX	± 0.15	X.XX*	$\pm 3^{\circ}$
X.XXX	± 0.10	X.XXX*	$\pm 2^{\circ}$

PROJ.	UNIT	SCALE
	mm	1:1

CUSTOMER DRAWING

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP-C7819-01**

TYPE : **Nano SIM Push/Pull 6P H1.1**

DRAWN **HXR 2024/11/20**

CHECKED **Henry 2024/11/20**

APPROVAL **Simon 2024/11/20**

DWG NO.:
DWG-C7819-01-01

SHEET
1/1

REVISION
1